

STD40NF02L

PRELIMINARY DATA

N-CHANNEL 20V - 0.0095 Ω - 40A $\,$ DPAK LOW GATE CHARGE STripFET^M POWER MOSFET

ТҮРЕ	V _{DSS}	R _{DS(on)}	I _D
STD40NF02L	20 V	< 0.0115 Ω	40 A

- TYPICAL $R_{DS(on)} = 0.0095 \Omega$
- TYPICAL Q_g = 35 nC @ 10V
- OPTIMAL R_{DS(on)} x Q_g TRADE-OFF
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED

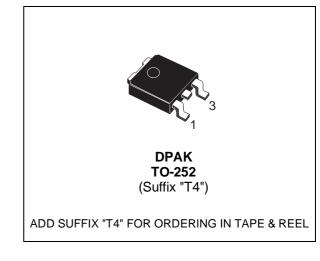
DESCRIPTION

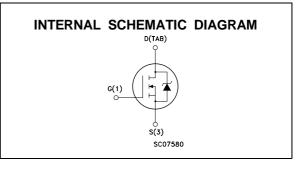
This application specific Power Mosfet is the third generation of STMicroelectronics unique "Single Feature SizeTM" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

APPLICATIONS

 SPECIFICALLY DESIGNED AND OPTIMISED FOR HIGH EFFICIENCY CPU CORE DC/DC CONVERTERS

ABSOLUTE MAXIMUM RATINGS





Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	20	V
V _{DGR}	Drain- gate Voltage (R_{GS} = 20 k Ω)	20	V
V _{GS}	Gate-source Voltage	± 20	V
I _D (●)	Drain Current (continuous) at T _c = 25 °C	20	А
I _D (●)	Drain Current (continuous) at T _c = 100 °C	20	А
I _{DM} (●●)	Drain Current (pulsed)	80	А
P _{tot}	Total Dissipation at $T_c = 25 \ ^{\circ}C$	55	W
	Derating Factor	0.37	W/ºC
T _{stg}	Storage Temperature	-65 to 175	°C
Ti	Max. Operating Junction Temperature	175	°C

(••) Pulse width limited by safe operating area

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THERMAL DATA

R _{thj-case}	Thermal Resistance Junction-case	Max	2.73	°C/W
R _{thj-amb}	Thermal Resistance Junction-ambient	Max	62.5	°C/W
Τι	Maximum Lead Temperature For Soldering	Purpose	300	°C

ELECTRICAL CHARACTERISTICS ($T_{case} = 25 \ ^{o}C$ unless otherwise specified) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A$ $V_{GS} = 0$	20			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating$ $T_c = 125 °C$			1 10	μΑ μΑ
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	$V_{GS} = \pm 20 V$			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250 \ \mu A$	1		2.5	V
R _{DS(on)}	Static Drain-source On Resistance			0.0095 0.015	0.0115 0.019	Ω Ω
I _{D(on)}	On State Drain Current	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $V_{GS} = 10 V$	20			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (*)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_{D} = 20 \text{ A}$		40		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 V$ f = 1 MHz $V_{GS} = 0$		1500 900 200		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Rise Time			20 170		ns ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 16 \text{ V } I_D = 20 \text{ A } V_{GS} = 10 \text{ V}$		36 5 10	45	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off Delay Time Fall Time			40 60		ns ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} (●)	Source-drain Current Source-drain Current (pulsed)				20 80	A A
V _{SD} (*)	Forward On Voltage	$I_{SD} = 20 \text{ A} V_{GS} = 0$			1.2	V
t _{rr}	Reverse Recovery Time	$I_{SD} = 20 A$ di/dt = 100 A/µs $V_{DD} = 15 V$ $T_i = 150 \ ^{\circ}C$		70		ns
Q _{rr}	Reverse Recovery Charge	(see test circuit, fig. 5)		105		μC
I _{RRM}	Reverse Recovery Current			2.4		A

(*) Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %

(•) Pulse width limited by safe operating area

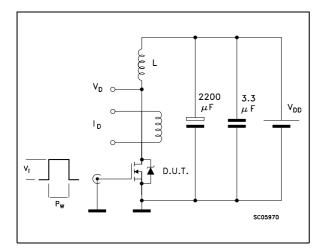


Fig. 1: Unclamped Inductive Load Test Circuit

Fig. 3: Switching Times Test Circuits For Resistive Load

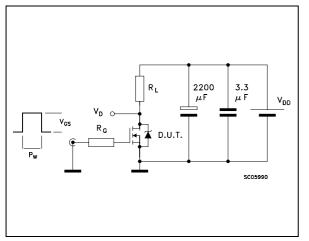


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

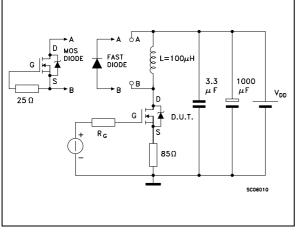


Fig. 2: Unclamped Inductive Waveform

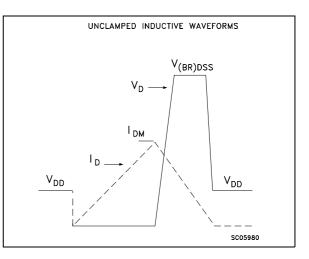
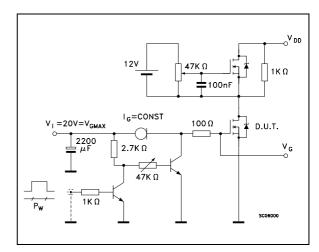


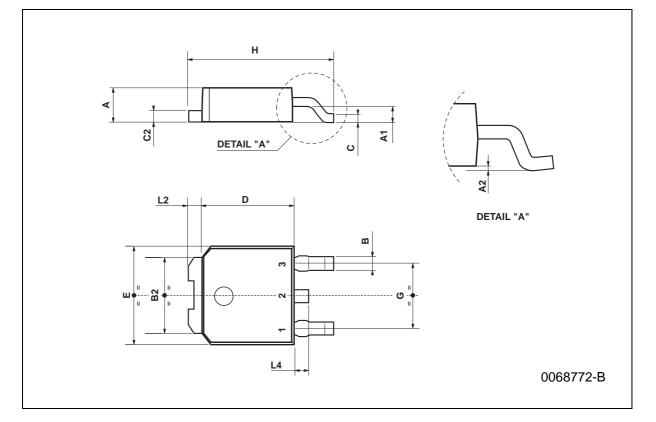
Fig. 4: Gate Charge test Circuit



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DIM.		mm			inch			
Divi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
А	2.2		2.4	0.086		0.094		
A1	0.9		1.1	0.035		0.043		
A2	0.03		0.23	0.001		0.009		
В	0.64		0.9	0.025		0.035		
B2	5.2		5.4	0.204		0.212		
С	0.45		0.6	0.017		0.023		
C2	0.48		0.6	0.019		0.023		
D	6		6.2	0.236		0.244		
Е	6.4		6.6	0.252		0.260		
G	4.4		4.6	0.173		0.181		
Н	9.35		10.1	0.368		0.397		
L2		0.8			0.031			
L4	0.6		1	0.023		0.039		





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